

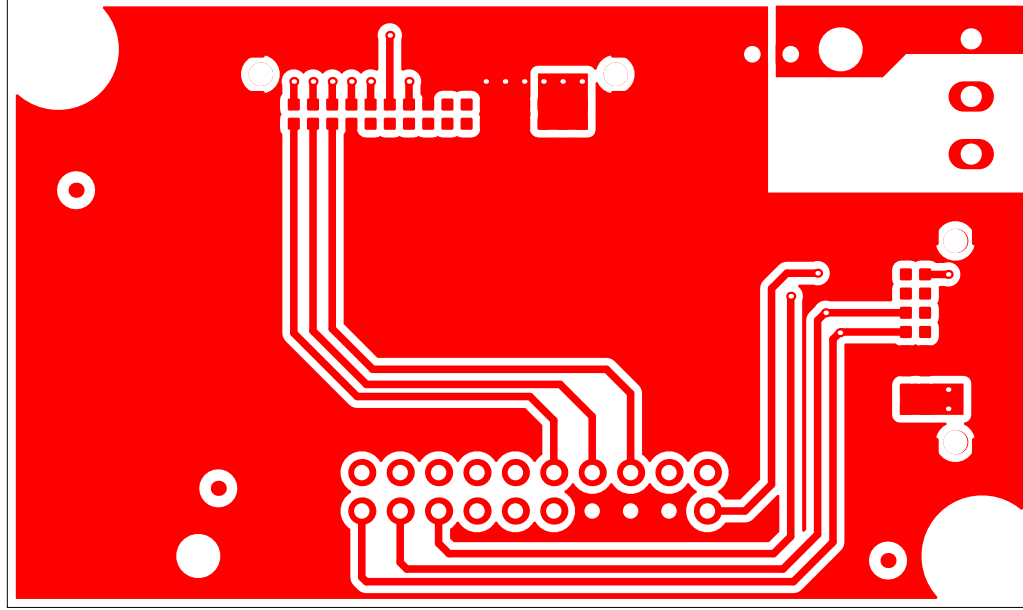
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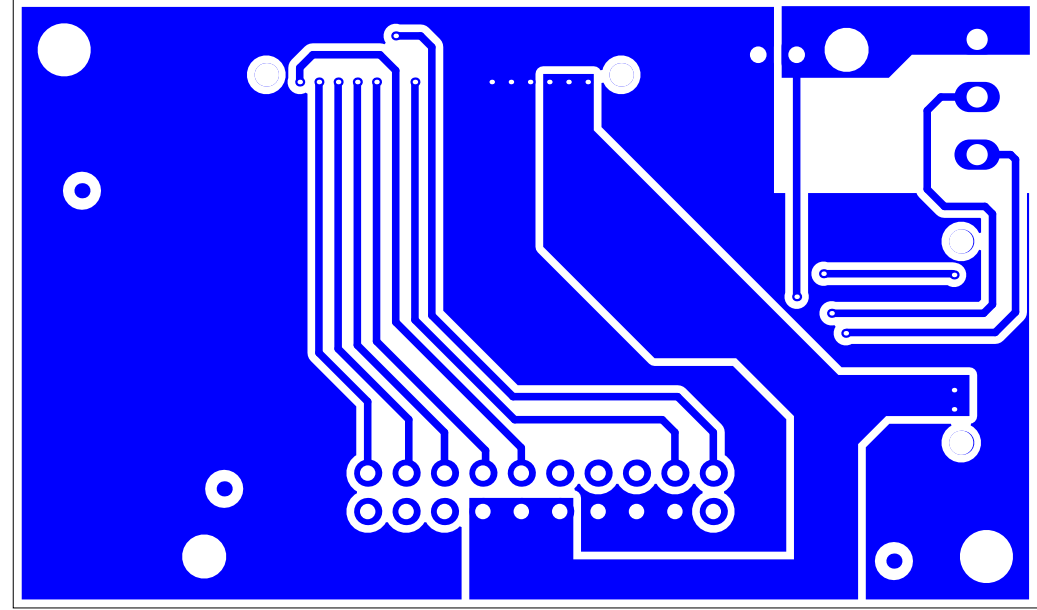
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	Ortam/Env Altium Designer	Syfnin/Shts / Sayfasi/Sht 1 / 6	Tarih/Date 30.06.2024	Deg Onay/Change Appr Hamit Can	Deg Tarihi/Chng Date 30.06.2024	Form A3

Bakır Katmanları / Copper Layers

Top Layer (Scale 2:1)



Bottom Layer (Scale 2:1)



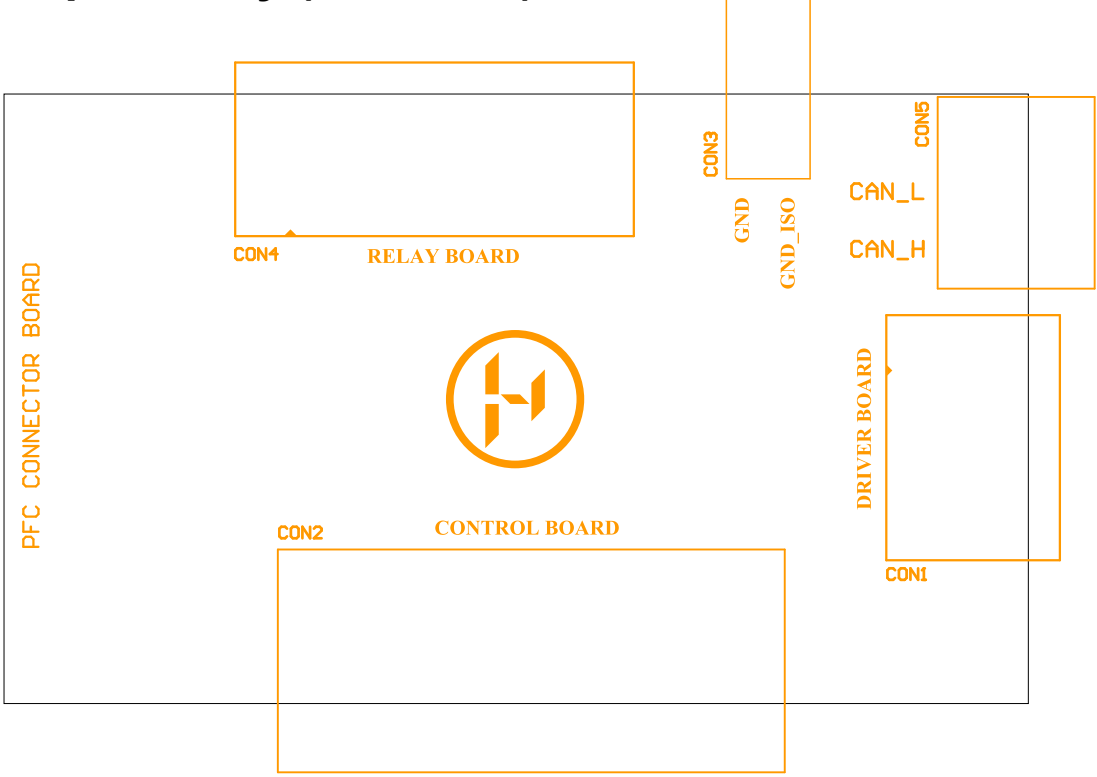
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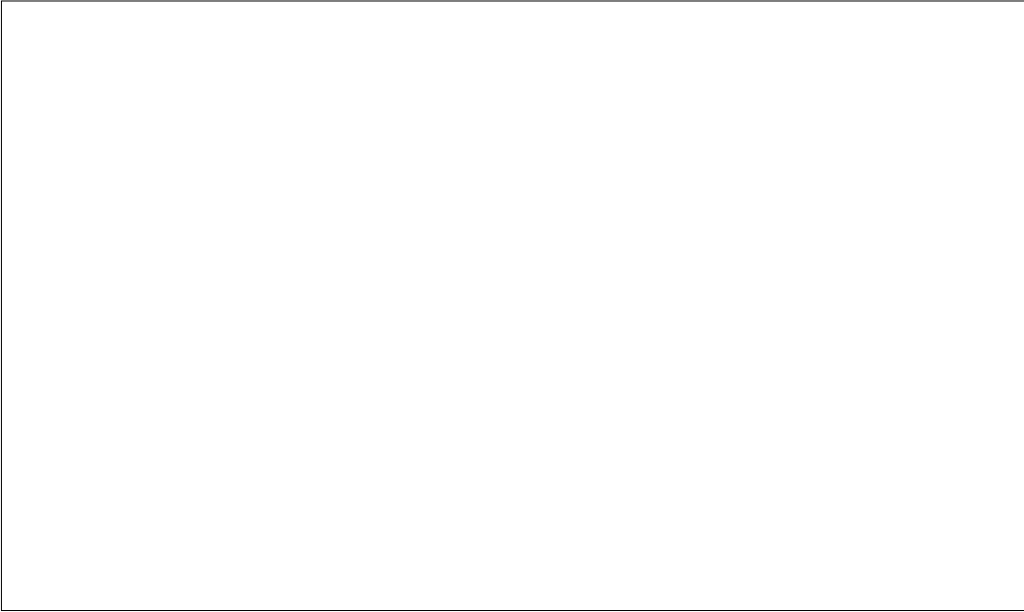
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Baskı Katmanları / Overlay Layers

Top Overlay (Scale 2:1)



Bottom Overlay (Scale 2:1)



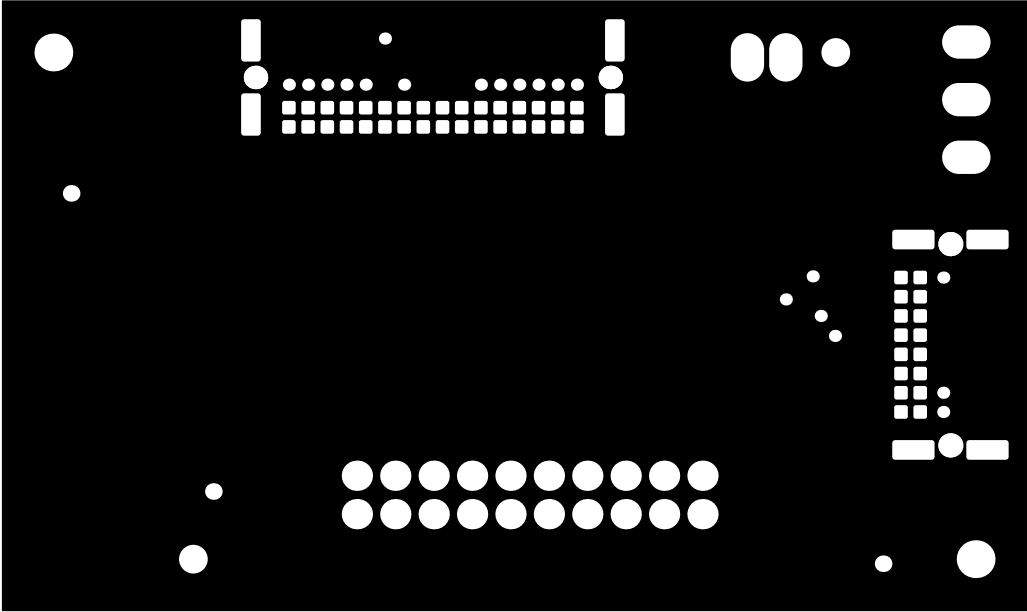
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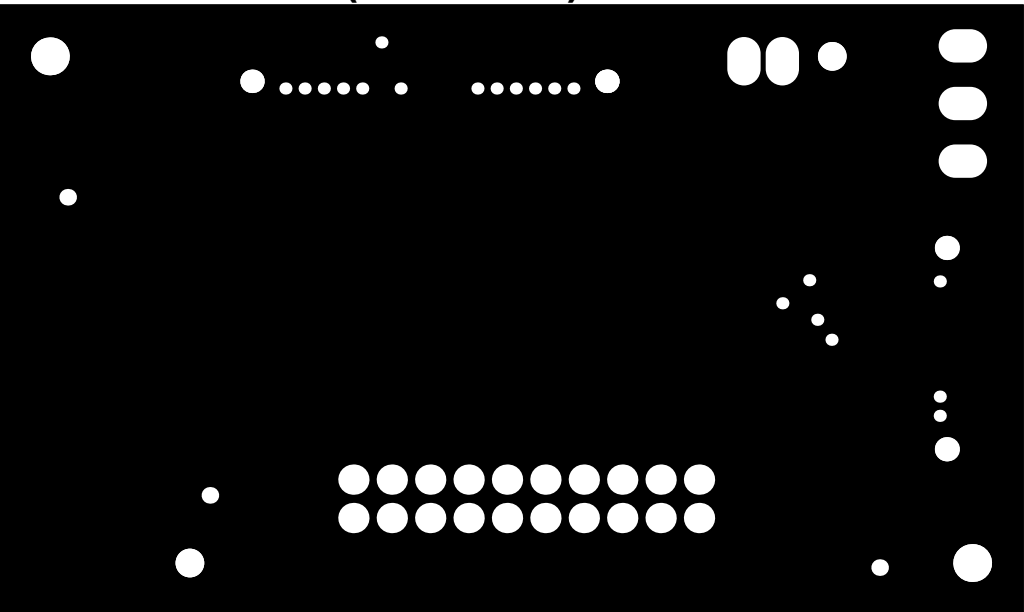
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Lehim Katmanları / Solder Layer

Top Solder (Scale 2:1)



Bottom Solder (Scale 2:1)



Notlar / Notes

No	Açıklama / Description

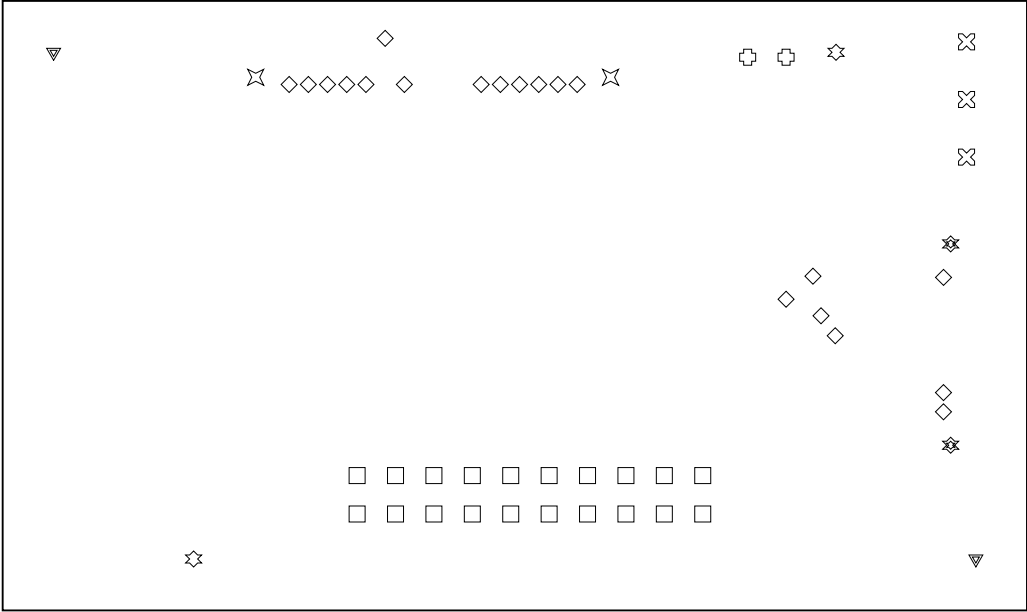
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Delik Tablosu ve Çizimi / Drill Table and Drawing

Drill Drawing View (Scale 2:1)



Delik Tablosu / Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Via / Pad	Pad Shape	Template	Hole Tolerance
◇	20	0.30mm(11.81mil)	Plated	Round	Via		v60h30	
□	20	1.02mm(40.16mil)	Plated	Round	Pad	Rounded	c180h102	
⊕	2	1.10mm(43.31mil)	Plated	Round	Pad	Rounded	r200_300h110r100	
⊗	3	1.40mm(55.12mil)	Plated	Round	Pad	Rounded	r200_300h140r100	
⊗	2	1.55mm(61.02mil)	Non-Plated	Round	Pad	Rounded	c155hn155m155	
⊗	2	1.60mm(62.99mil)	Non-Plated	Round	Pad	Rounded	c160hn160m160	
☆	2	1.90mm(74.80mil)	Plated	Round	Pad	Rectangular	s0h190	
▽	2	2.50mm(98.43mil)	Non-Plated	Round	Pad	Rounded	c20hn250	
53 Total								

Notlar / Notes

No	Açıklama / Description

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Katman Tasarımı / Stack-Up Design

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.03mm(1.00mil)	SM-001	Solder Mask	GTS
PbSn	Top Surface Finish	0.02mm(0.79mil)		Surface Finish	
CF-004	Top Layer	0.04mm(1.38mil)		Signal	GTL
Core		1.50mm(59.00mil)	Core-043	Dielectric	
CF-004	Bottom Layer	0.04mm(1.38mil)		Signal	GBL
PbSn	Bottom Surface Finish	0.02mm(0.79mil)		Surface Finish	
Surface Material	Bottom Solder	0.03mm(1.00mil)	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.66mm(65.33mil)					

PCB Üretim Özeti / PCB Manufacturing Summary

Board ID:	PEU_RELAY_INTERFACE_BOARD
Quantity:	20
Dimensions [mm]:	40,3 x 67,75mm
Layers:	2
Substrate:	FR-4, Tg:150-160
Total Thickness:	1.6mm
Copper Weight:	Top/Bottom: 1 Oz
Surface Finish:	Lead Free HASL
Controlled Impedance:	No
Panel Separating Way:	No
Number of Different Boards:	1
Via Process:	Tented, Filled w/Resin
Solder Mask Color:	Green
Silkscreen Color:	White
Minimum Hole Size [mm]:	0,30mm
Minimum Clearance / Spacing [mm]:	0.2mm
V-CUT:	Yes
Via Fill:	Yes
Additional Notes:	Class-2

Notlar / Notes

No	Açıklama / Description
1	PCB üretimi yukarıdaki tablo referans alınarak yapılmalıdır.

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	Ortam/Env Altium Designer	Syfnin/Shts / Sayfasi/Sht 6 / 6	Tarih/Date 30.06.2024	Deg Onay/Change Appr Hamit Can	Deg Tarihi/Chng Date 30.06.2024	Form A3